

**Amendments to the Abstract**

Please replace the Abstract with the following:

Methods for forming interposer substrates include providing a rectangular substantially planar substrate including a dielectric material and forming an elongated interconnect slot that includes a plurality of longitudinally adjacent segments separated by at least one transversely extending crosspiece. The interconnect slot is sized and configured to expose bond pads of a semiconductor die through the substantially planar substrate when the semiconductor die is placed on the substantially planar substrate. The interconnect slot may be formed by milling through the substrate, and the crosspiece may include at least one unmilled portion of the substrate lying intermediate opposing ends of the interconnect slot. Filleted side edges may be produced on the crosspiece during milling. The crosspiece may be located substantially at a longitudinal midpoint of the interconnect slot. The interconnect slot may have a length of about 67% or more of a length of the substrate.